

|                          |                           |                                     |                     |
|--------------------------|---------------------------|-------------------------------------|---------------------|
| <b>PCN Number:</b>       | 20191205000               | <b>PCN Date:</b>                    | Dec. 9, 2019        |
| <b>Title:</b>            | Datasheet for DRV8847     |                                     |                     |
| <b>Customer Contact:</b> | PCN Manager               | <b>Dept:</b>                        | Quality Services    |
| <b>Change Type:</b>      |                           |                                     |                     |
| <input type="checkbox"/> | Assembly Site             | <input type="checkbox"/>            | Design              |
| <input type="checkbox"/> | Assembly Process          | <input checked="" type="checkbox"/> | Data Sheet          |
| <input type="checkbox"/> | Assembly Materials        | <input type="checkbox"/>            | Part number change  |
| <input type="checkbox"/> | Mechanical Specification  | <input type="checkbox"/>            | Test Site           |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/>            | Test Process        |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Bump Site     |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Bump Material |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Bump Process  |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Fab Site      |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Fab Materials |
| <input type="checkbox"/> |                           | <input type="checkbox"/>            | Wafer Fab Process   |

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



DRV8847

SLVSE65B – JULY 2018 – REVISED SEPTEMBER 2019

#### Changes from Revision A (July 2018) to Revision B

Page

|  |    |
|--|----|
| • Changed the Low On-State Resistance to be the indicated value when VM > 5 V .....  | 1  |
| • Changed nFAULT pin type to OD/I .....  | 5  |
| • Changed VM description to indicate 0.1-uF capacitor should be ceramic .....  | 5  |
| • Changed digital pin voltage (IN1, IN2, IN3, IN4, TRQ, nSLEEP, nFAULT, SCL, SDA) maximum voltage from 5.5 V to 5.75 V .....   | 6  |
| • Changed the Phase node pin voltage specification's name to Continuous phase node pin voltage .....   | 6  |
| • Added for ISEN12, ISEN34 specification a footnote stating transients of +- 1V for less than 25 ns are acceptable .....   | 6  |
| • Added for both Peak drive current (OUT1, OUT2, OUT3, OUT4) specifications a footnote stating Power dissipation and thermal limits must be observed .....   | 6  |
| • Changed V(ESD) specification's value to 4000 V .....   | 6  |
| • Changed the V <sub>IL</sub> specification to be two specifications based on test conditions VM < 7 V and VM >= 7 V .....   | 7  |
| • Changed the I <sub>IH</sub> specification's minimum value to 18 uA for test condition IN1, IN2, IN3, IN4, TRQ, VIN = 5 V and to 10 uA for test condition nSLEEP, V <sub>IN</sub> = minimum (VM, 5 V) ..... | 7  |
| • Added to I <sub>OCP</sub> specification a minimum value .....  | 8  |
| • Changed pin naming of Block Diagram for DRV8847S figure .....  | 16 |
| • Deleted ceramic from C <sub>VM1</sub> .....  | 17 |
| • Changed the relay or solenoid coils load bullet item for more clarity .....  | 24 |
| • Added sentence to clarify nFAULT pin behavior when open load is detected .....   | 36 |
| • Added sentence to clarify nFAULT pin behavior during power-up .....  | 39 |
| • Added an Open Load Implementation section .....  | 53 |
| • Added a Layout Recommendation of 16-Pin QFN Package for Double Layer Board figure .....  | 62 |

The datasheet number will be changing.

|               |              |            |
|---------------|--------------|------------|
| Device Family | Change From: | Change To: |
| DRV8847□      | SLVSE65A     | SLVSE65B   |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DRV8847>

#### Reason for Change:

To accurately reflect device characteristics.

|   |            |             |             |
|---|------------|-------------|-------------|
| <b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>                     |            |             |             |
| No anticipated impact. This is a specification change announcement only. There are no changes to the actual device. |            |             |             |
| <b>Changes to product identification resulting from this PCN:</b>   |            |             |             |
| None.   |            |             |             |
| <b>Product Affected:</b>  |            |             |             |
| DRV8847PWPR   | DRV8847PWR | DRV8847RTER | DRV8847RTET |
| DRV8847SPWR   |            |             |             |

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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